



Digital Twins in Industry

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Message from the Guest Editors

Digital twin technology has seen rapid growth in the last ten years. It is a natural progression and fusion of many emerging technologies such as Internet of Things; wireless communication; sensors technology; cloud computing; artificial intelligence; big data analytics; data integration; data visualization in the form of virtual and augmented reality. It has been recognized as one of the pillars of Industry 4.0—the major effort in integrating all the elements in the manufacturing industry—toward achieving seamless control and communications between labor, machines, and management.

This Special Issue will examine the industrial applications and implementation of digital twin technology across various industrial, commercial, and financial sectors. It will be particularly useful to learn of the approaches which have been undertaken by the industry in dealing with issues such as, for example, cybersecurity and intellectual property.





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Message from the Editor-in-Chief

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